



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

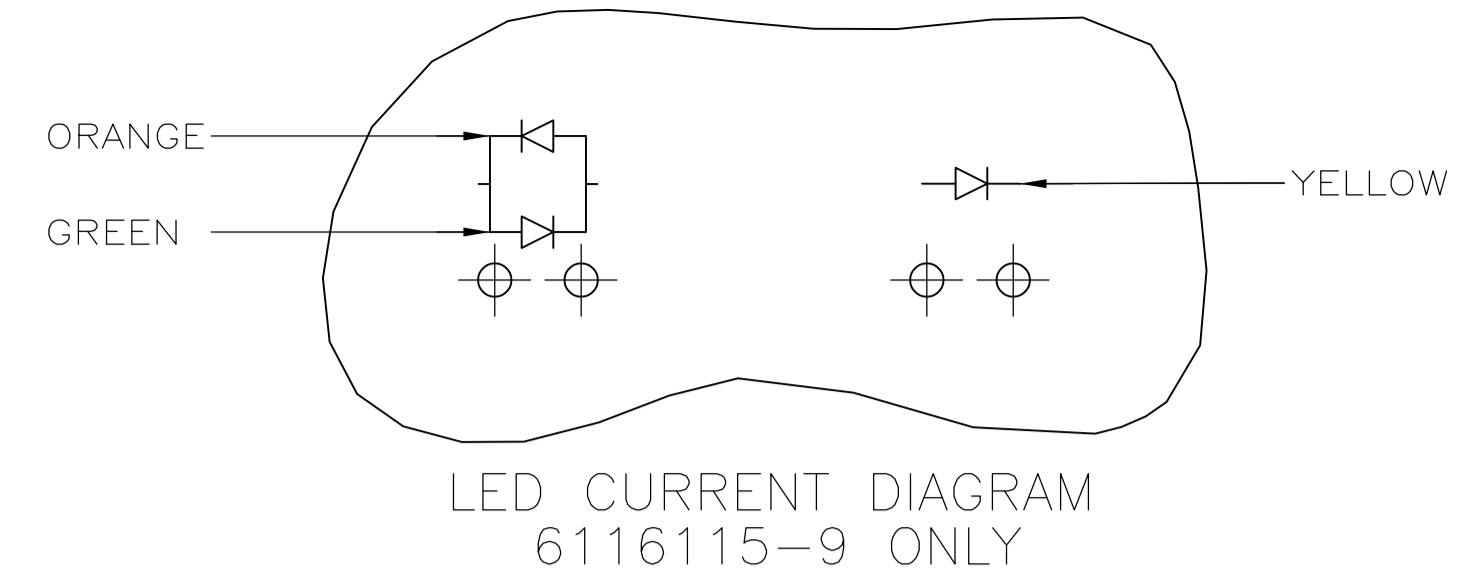
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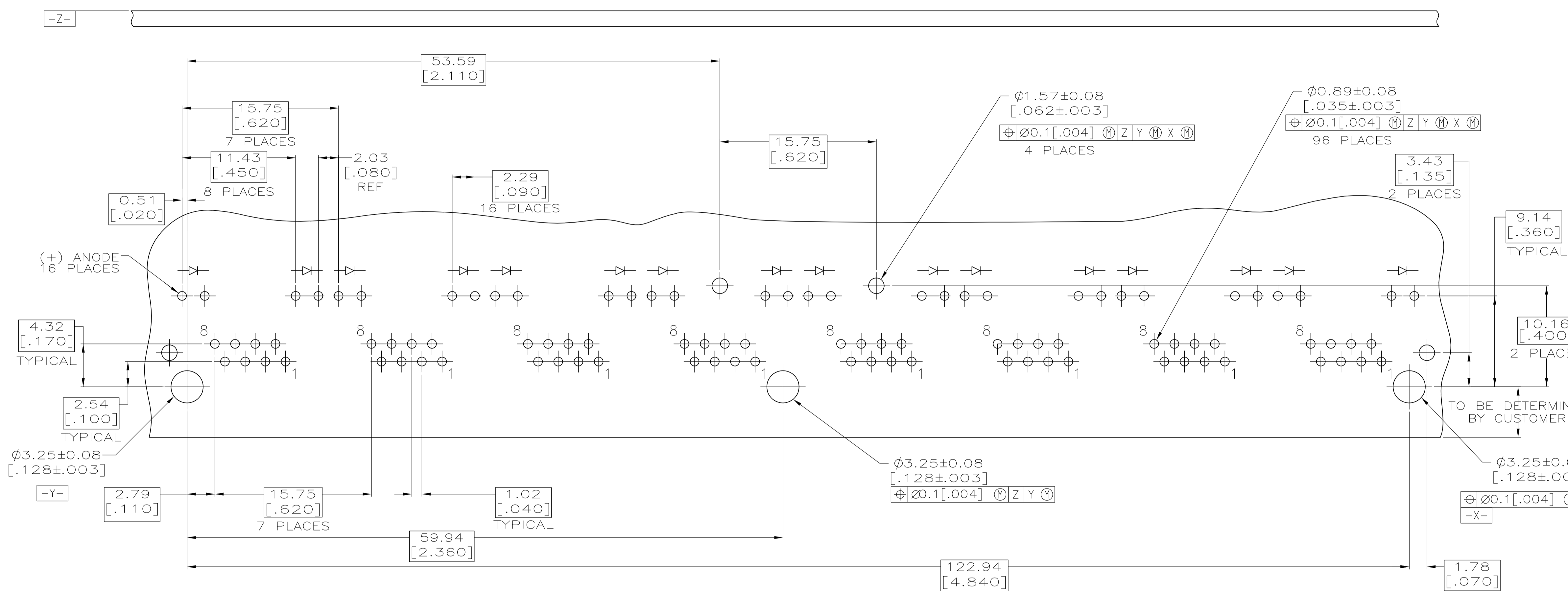


LOC		DIST		REVISIONS			
AA	22	F	LTR	DESCRIPTION	DATE	DMN	APVD
		A		REV PER EC 0511-0201-04	09JUN2005	LV	SF
		A1		REVISED PER ECO-09-024927	11NOV09	KK	AEG

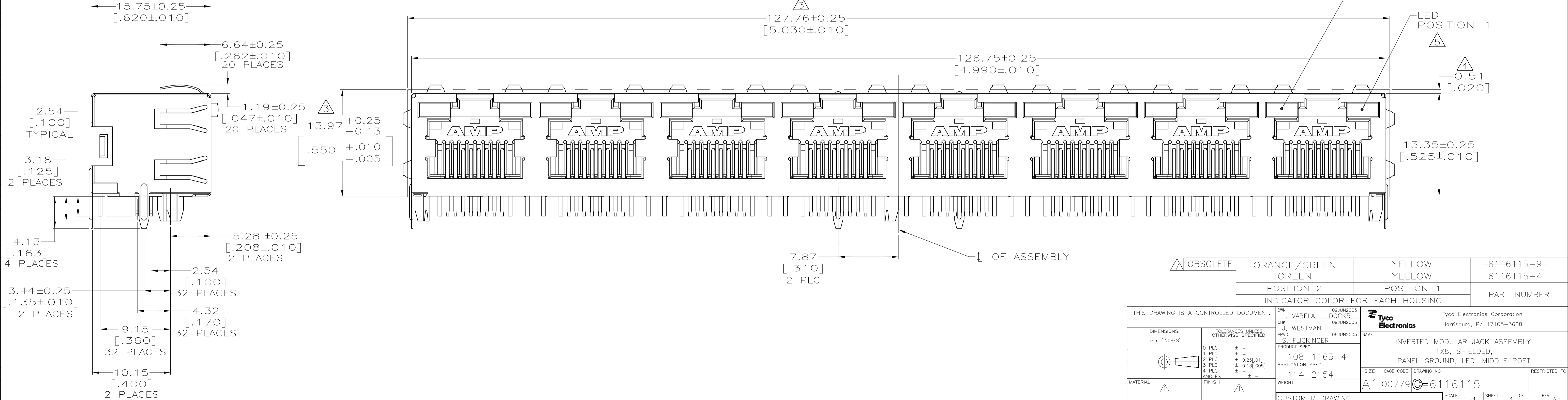


MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27µm[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm[.000050] MINIMUM THICK NICKEL.
 SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MINIMUM SATIN NICKEL WITH 2.03µm[.000080] MINIMUM HOT TIN DIPPED ON PCB GROUND TABS.
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89µm[.0003500] THICK Sn/Cu OVER 2.03µm[.000080] THICK Ag OVER 1.02µm[.000040] THICK Cu OVER 3.56µm[.000140] THICK Ni OVER 1.02µm[.000040] Cu UNDERPLATE.

- 2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
- △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- △ SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
- 6. THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.
- △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)



INDICATOR COLOR FOR EACH HOUSING	POSITION 2	POSITION 1	PART NUMBER
ORANGE/GREEN	YELLOW	YELLOW	-6116115-9-
GREEN	YELLOW	YELLOW	6116115-4

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIMENSIONS: mm [INCHES] TOLERANCES UNLESS OTHERWISE SPECIFIED: 0. PLC ± - 1. PLC ± - 2. PLC ± 0.25[.01] 3. PLC ± 0.13[.005] 4. PLC ± - ANGLES ± -		THIS DRAWING IS A CONTROLLED DOCUMENT. DIM: L. VARELA - DOCKS CHK: J. WESTMAN APVD: S. FLICKINGER PRODUCT SPEC: 108-1163-4 APPLICATION SPEC: 114-2154 MATERIAL: △ FINISH: △		Tyco Electronics Corporation Harrisburg, Pa 17105-3608 NAME: INVERTED MODULAR JACK ASSEMBLY, 1X8, SHIELDED, PANEL GROUND, LED, MIDDLE POST SIZE: 108-1163-4 CASE CODE: 114-2154 DRAWING NO: 6116115 RESTRICTED TO: △ CUSTOMER DRAWING: △	
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